

ABSTRACT OF THE DISCLOSURE

POLISHING METHOD AND POLISHING APPARATUS

5 A polishing method that can stabilize an intensity of light emitted by a flash light source and can polish a substrate while measuring film thickness at more measurement points is disclosed. The polishing method includes: causing a first flash light source and a second flash light source to emit light multiple times at different timings to cast the light on the substrate through an optical sensor head while the optical sensor head is moving across the
10 substrate, and capture reflected light from the substrate through the optical sensor head by a spectrometer; generating a spectrum of the reflected light; and determining a film thickness of the substrate from the spectrum.

FIG. 4